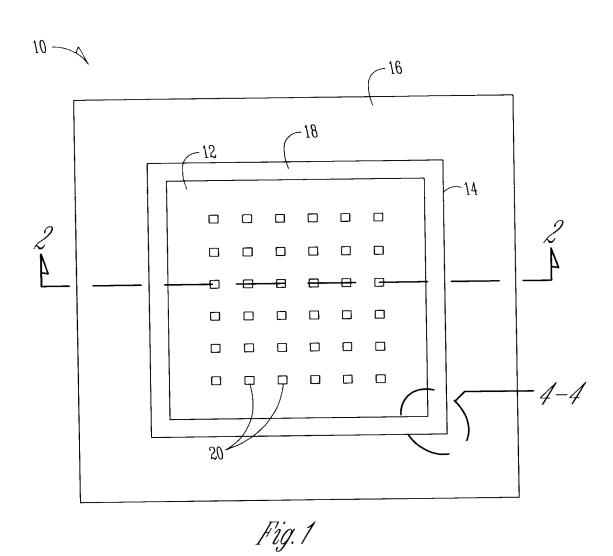
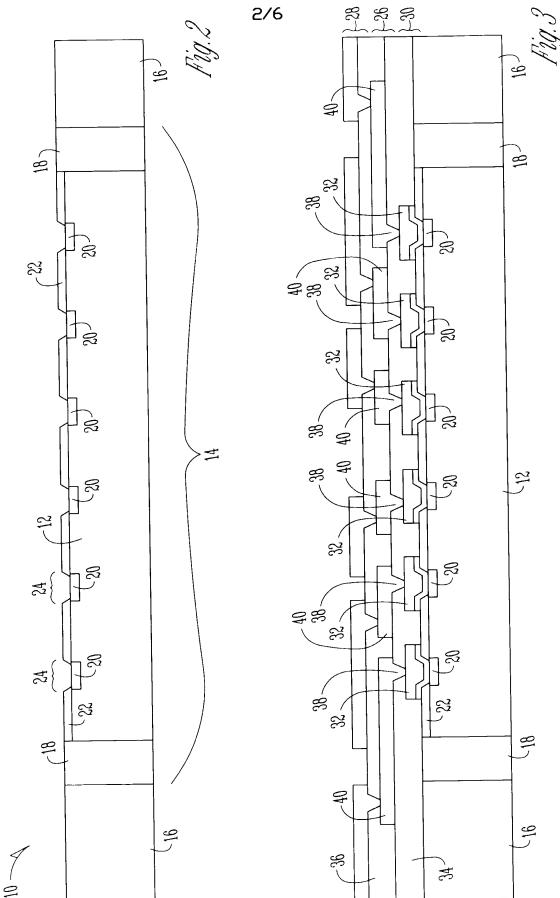
TITLE: POLY ENCAPSULATION MATERIAL WITH FIBROUS FILL R USE IN MICROELECTRONIC CIRCUIT PACKAGING INVENTORS NAME: Steven Towle DOCKET NO.: 884.415US1





ENCAPSULATION MATERIAL WITH FIBROUS FILE OR USE IN MICROELECTRONIC CIRCUIT PACKAGING INVENTORS NAME: Steven Towle DOCKET NO.: 884.415US1 TITLE: POLY

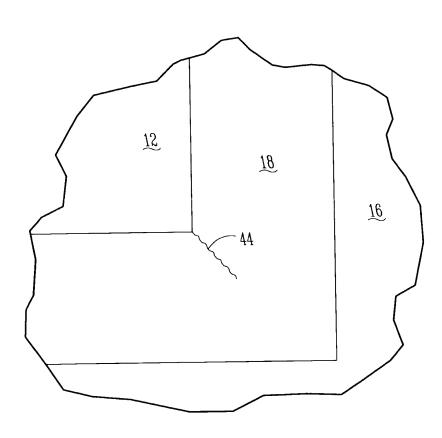


Fig. 4

ENCAPSULATION MATERIAL WITH FIBROUS FILL MICROELECTRONIC CIRCUIT PACKAGING INVENTORS NAME: Steven Towle DOCKET NO.: 884.415US1 R USE IN TITLE: POLY

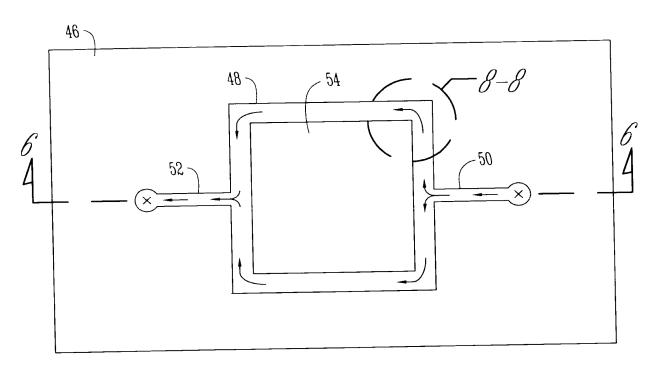


Fig. 5

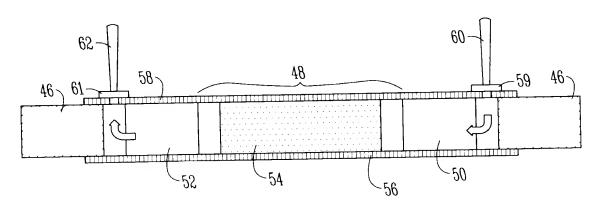


Fig. 6

ENCAPSULATION MATERIAL WITH FIBROUS FILL MICROELECTRONIC CIRCUIT PACKAGING INVENTORS NAME: Steven Towle DOCKET NO.: 884.415US1 OR USE IN TITLE: POLY

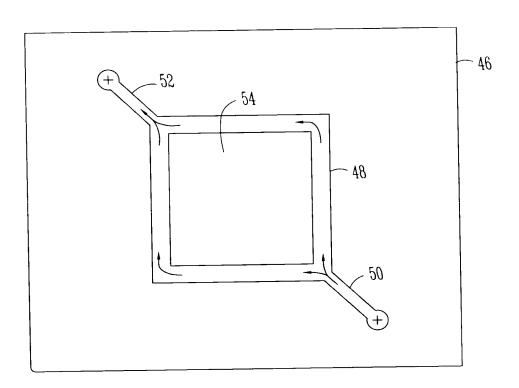


Fig. 7 -64  $\underbrace{46}$ 48 64~ <u>54</u> Fig. 8

ENCAPSULATION MATERIAL WITH FIBROUS FILL MICROELECTRONIC CIRCUIT PACKAGING INVENTORS NAME: Steven Towle DOCKET NO.: 884.415US1 OR USE IN TITLE: POLY

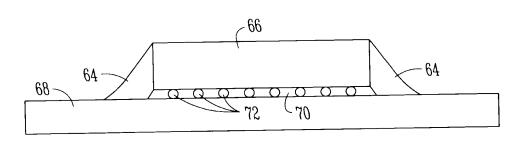


Fig. 9

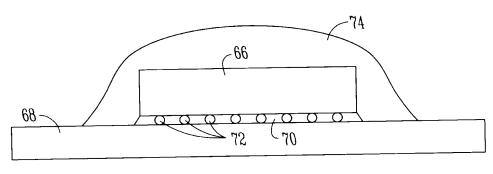


Fig. 10

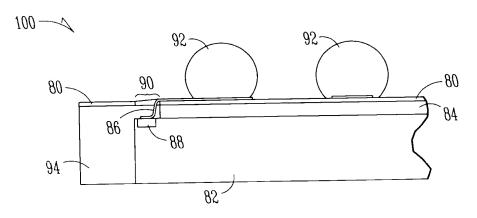


Fig. 11